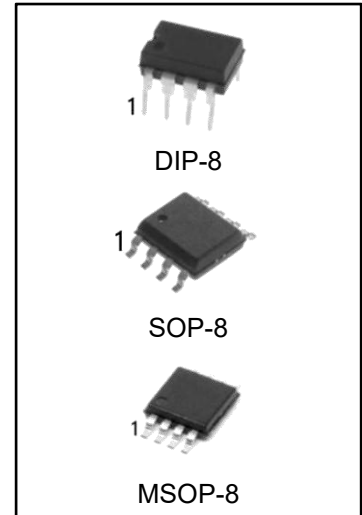


CMOS general purpose timer

Features

- Exact equivalent in most cases for SE/NE555.
- Low Supply Current.
- High speed operation – 500 kHz guaranteed.
- Wide operation supply voltage range – 2 to 18 volts.
- Timing from microseconds through hours.
- Operates in both astable and monostable modes.
- Adjustable duty cycle.
- High output source/sink driver can drive TTL/CMOS



Ordering Information

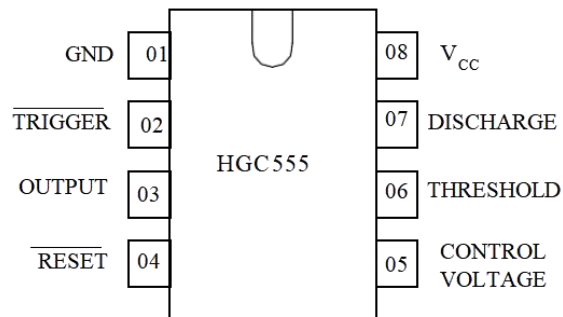
DEVICE	Package Type	MARKING	Packing	Packing Qty
HGC555IN	DIP-8	HGC555I	TUBE	2000pcs/box
HGC555IM/TR	SOP-8	HGC555I	REEL	2500pcs/reel
HGC555IMM/TR	MSOP-8	C555I	REEL	3000pcs/reel

General Description

The HGC555 is CMOS RC timers providing significantly improved performance over the standard SE/NE555 and 355 timers, while at the same time being direct replacements for those devices in most applications. Improved parameters include low supply current, wide operating supply voltage range, low THRESHOLD, TRIGGER and RESET currents, no crowbaring of the supply current during output transitions, higher frequency performance and no requirement to decouple CONTROL VOLTAGE for stable operation.

Specifically, the HGC555 is stable controller capable of producing accurate time delays of frequencies.

Pin Assignment



Truth Table

THRESHOLD	TRIGGER	RESET	OUTPUT	DISCHARGE
X	X	L	L	ON
$> 2/3 V_{CC}$	$> 1/3 V_{CC}$	H	L	ON
$< 2/3 V_{CC}$	$> 1/3 V_{CC}$	H	STABLE	STABLE
X	$< 1/3 V_{CC}$	H	H	OFF

Maximum Ratings And Recommended Operating Conditions

Parameter, unit	Symbol	Recommended operating conditions		Maximum ratings	
		Value		Value	
		min	max	min	max
Supply Voltage, V	V _{CC}	2.0	18.0	0	18.0
Output Current, mA	I _o	-	20	-	100
Input Voltage, V	V _{TH} , V _{TRIG} , V _{RST}	-	-	-0.3	V _{CC} +0.3
Power Dissipation, mW	P _D	-	-	-	200
Operating Temperature, °C	TOPR	-40	85	-40	85
Storage Temperature, °C	TSTG	-	-	-65	150
Lead Temperature, 1 mm from Case for 10 Seconds, °C	TSOLDER	-	-		245

Note: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but specific performance is not ensured.

Dc Electrical Characteristics (Voltages Referenced to GND)

Parameter, units	Symbol	Test Conditions		Value		Temperature, °C
		I _{OL} , I _{OH}	V _{CC} , B	min	max	
Threshold Voltage, V	V _{TH}		5.0	0.65 V _{CC}	0.70 V _{CC}	25 ± 10
				0.60 V _{CC}	0.80 V _{CC}	-20, 70
Trigger voltage, V	V _{TRIG}		5.0	0.31 V _{CC}	0.36 V _{CC}	25 ± 10
				0.28 V _{CC}	0.40 V _{CC}	-20, 70
Reset voltage, V	V _{RST}		2.0	0.4	1.0	25 ± 10
			18.0			
			2.0	0.2	1.5	-20, 70
			18.0			
Control Voltage Lead, V	V _{CV}			0.65 V _{CC}	0.69 V _{CC}	25 10
				0.60 V _{CC}	0.80 V _{CC}	-20, 70
Output voltage Low, V	V _{OL}	I _{OL} = 3.2 mA	5.0		0.4	25 ± 10
		I _{OL} = 20 mA	15.0		1.0	
		I _{OL} = 3.2 mA	5.0		0.6	-20, 70
		I _{OL} = 20 mA	15.0		1.5	
Output voltage High, V	V _{OH}	I _{OH} = -0.8 mA	5.0	4.0		25 ± 10
			15.0	14.3		
			5.0	3.5		-20, 70
			15.0	14.0		
Supply Current, μA	I _{CC}		2.0		200	25 ± 10
			18.0		300	
			2.0		400	-20, 70
			18.0		600	

Ac Electrical Characteristics

Parameter, unit	Symbol	Test Conditions		Value		Temperature, °C	
		R _L , C _L	V _{CC} , V	Min	Max		
Rise (Fall) Time of Output, ns	t _{THL} , t _{TLH}	R _L = 10 M Ω , C _L = 10 pF	5.0	35	75	25 \pm 10	
				70	150	-20, 70	
Guaranteed Max Osc Freq, kHz	f _{MAX}	Astable Operation	2.0-18.0	500		25 \pm 10	
				200		-20, 70	
Initial accuracy, %				5			
Drift with Temperature, %/°C	f	R _L = 1 - 100 k Ω C _L = 0.1 μ F	5.0		0.02	-20, 70	
					10.0		0.03
					15.0		0.06
Drift with Supply Voltage, %/B	f		5.0		3	25 \pm 10	
						6	-20, 70

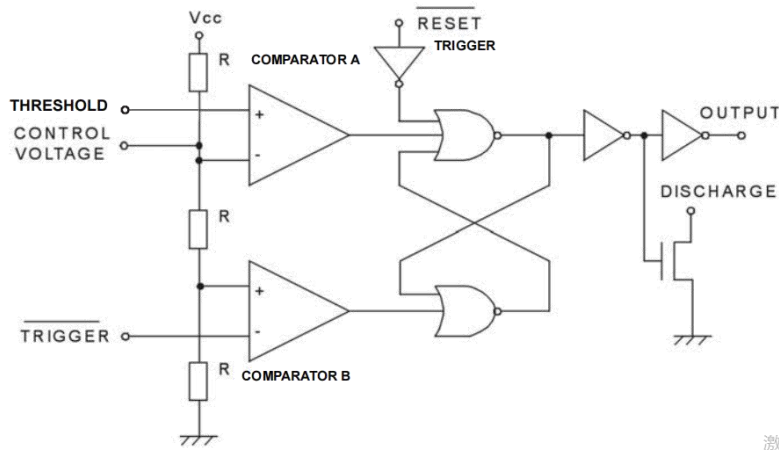


Figura 1. Block Diagram

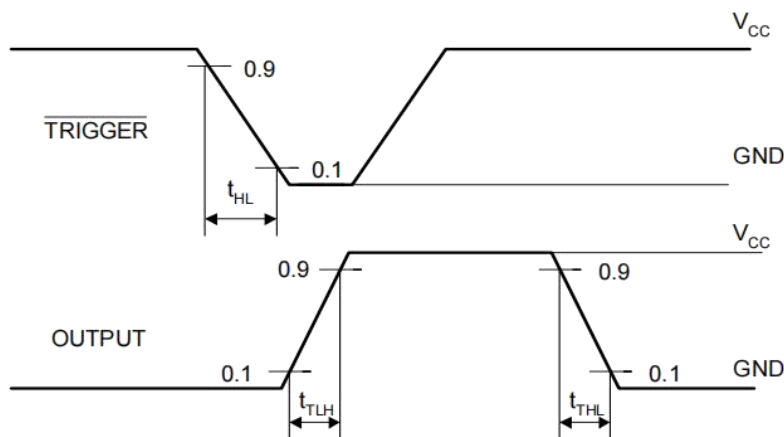
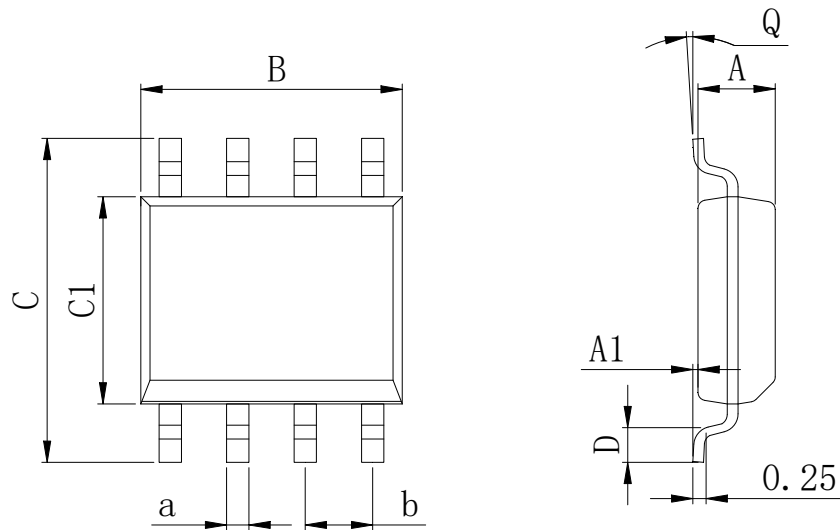


Figura 2. Switching Waveforms

Physical Dimensions

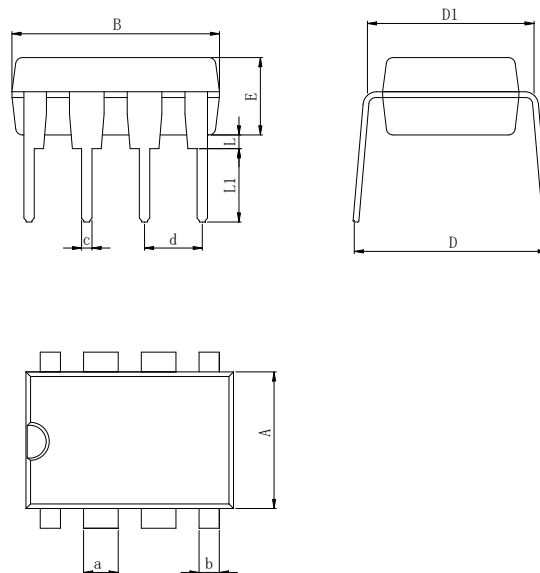
SOP-8



Dimensions In Millimeters(SOP-8)

Symbol:	A	A1	B	C	C1	D	Q	a	b
Min:	1.35	0.05	4.90	5.80	3.80	0.40	0°	0.35	1.27 BSC
Max:	1.55	0.20	5.10	6.20	4.00	0.80	8°	0.45	

DIP-8

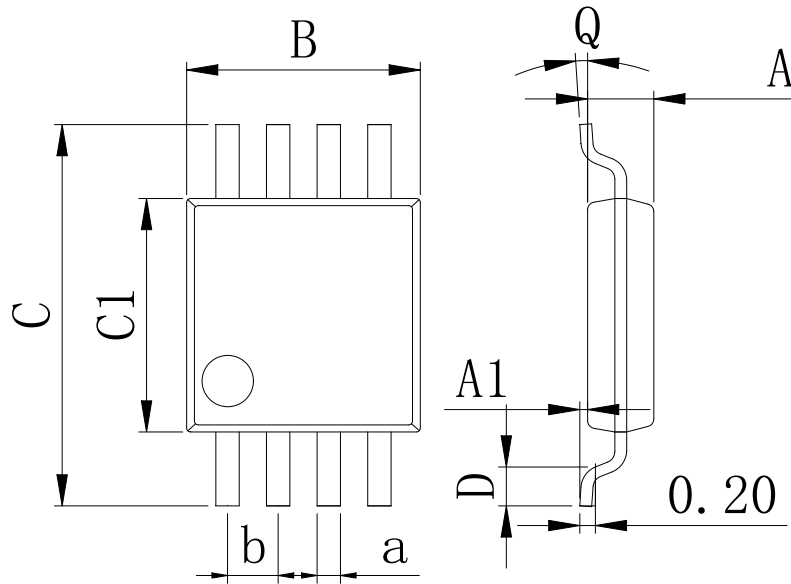


Dimensions In Millimeters(DIP-8)

Symbol:	A	B	D	D1	E	L	L1	a	b	c	d
Min:	6.10	9.00	8.10	7.42	3.10	0.50	3.00	1.50	0.85	0.40	2.54 BSC
Max:	6.68	9.50	10.9	7.82	3.55	0.70	3.60	1.55	0.90	0.50	

Physical Dimensions

MSOP-8



Dimensions In Millimeters(MSOP-8)									
Symbol:	A	A1	B	C	C1	D	Q	a	b
Min:	0.80	0.05	2.90	4.75	2.90	0.35	0°	0.25	0.65 BSC
Max:	0.90	0.20	3.10	5.05	3.10	0.75	8°	0.35	

Revision History

DATE	REVISION	PAGE
2019-3-6	New	1-9
2023-9-13	Update encapsulation type , Update Lead Temperature 、 Updated DIP-8 dimension、 Add annotation for Maximum Ratings、 Update Ordering Information	1、 3、 6

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